www.omseni.com

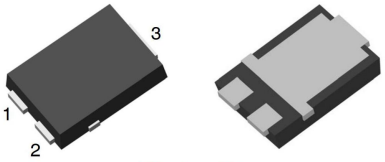
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SCHOTTKY BARRIER
RECTIFIER, 8 AMPERES
100 VOLTS

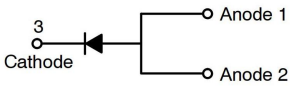
NRTS8100PFST3G

Schottky Barrier Rectifier, Trench-based

This TO−277 trench Schottky rectifier provides fast switching performance in a compact thermally efficient package. The TO−277 package provides an excellent alternative to the DPAK, offering thermal performance nearly as good in a package occupying less than half the board space. Its low profile makes it a good option for flat panel display and other applications with limited vertical clearance. The device offers low leakage over temperature making it a good match for applications requiring low quiescent current.



TO−277−3LD
CASE 340CZ



Features

- Package Provides Capability of Inspection and Probe After Board Mounting
- Low Forward Voltage Drop
- 175°C Operating Junction Temperature
- These Devices are Pb−Free, Halogen Free/BFR Free and are RoHS Compliant

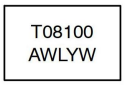
Mechanical Characteristics:

- Case: Epoxy, Molded
- Epoxy Meets Flammability Rating UL 94−0 @ 0.125 in.
- Lead Finish: 100% Matte Sn (Tin)
- Lead and Mounting Surface Temperature for Soldering Purposes: 260°C Max. for 10 Seconds
- Device Meets MSL 1 Requirements

Applications

- Excellent Alternative to DPAK in Space−Constrained Automotive Applications
- Low Leakage for Higher Temperature Operation
- Output Rectification in Compact Portable Consumer Applications
- Freewheeling Diode used with Inductive Loads

MARKING DIAGRAM



T08100	= Specific Device Code
A	= Assembly Location
Y	= Year
W	= Work Week
WL	= Wafer Lot

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MAXIMUM RATINGS

Rating	Symbol	Value	Unit
Peak Repetitive Reverse Voltage Working Peak Reverse Voltage DC Blocking Voltage	V_{RRM} V_{RWM} V_R	100	V
Average Rectified Forward Current (T_C = 164°C)	$I_{F(AV)}$	8	A
Peak Repetitive Forward Current, (T_C = 162°C, Square Wave, Duty = 0.5)	I_{FRM}	16	A
Storage Temperature Range	T_{stg}	−65 to +175	°C
Operating Junction Temperature	T_J	−55 to +175	°C
ESD Rating (Human Body Model)	ESD_{HBM}	3B	
ESD Rating (Charged Device Model)	ESD_{CDM}	C5	

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

THERMAL CHARACTERISTICS

Characteristic	Symbol	Max	Unit
Thermal Resistance, Junction−to−Ambient (Assumes 600 mm^2, 1 oz. copper bond pad on a FR4 board)	$R_{\theta JA}$	70	°C/W
Thermal Resistance, Junction−to−Case, Top (Assumes 600 mm^2, 1 oz. copper bond pad on a FR4 board)	$R_{\theta JCT}$	62	°C/W
Thermal Resistance, Junction−to−Case, Bottom (Assumes 600 mm^2, 1 oz. copper bond pad on a FR4 board)	$R_{\theta JCB}$	2.2	°C/W

ELECTRICAL CHARACTERISTICS

Characteristic	Symbol	Typ	Max	Unit
Instantaneous Forward Voltage (Note 1) (i_F = 4 A, T_J = 25°C) (i_F = 4 A, T_J = 125°C) (i_F = 8 A, T_J = 25°C) (i_F = 8 A, T_J = 125°C)	v_F	 0.60 0.55 0.76 0.66	 − − 0.82 0.70	V
Instantaneous Reverse Current (Note 1) (Rated dc Voltage, T_J = 25°C) (Rated dc Voltage, T_J = 125°C)	i_R	 3.0 2.5	 100 20	 μA mA
Junction Capacitance (V_R = 1 V, T_J = 125°C, 1 MHz)	C_J	 660		pF

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

1. Pulse Test: Pulse Width = 300 μs, Duty Cycle ≤ 2.0%.

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TYPICAL CHARACTERISTICS

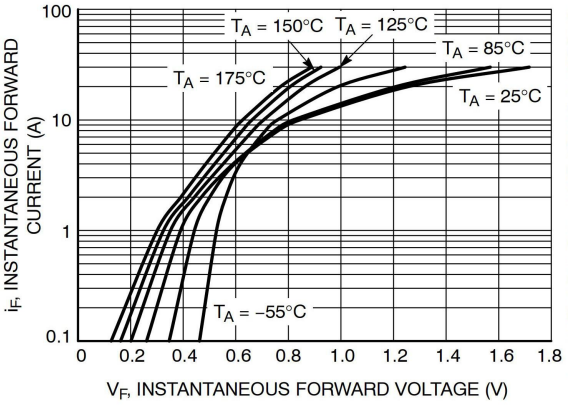


Figure 1. Typical Instantaneous Forward Characteristics

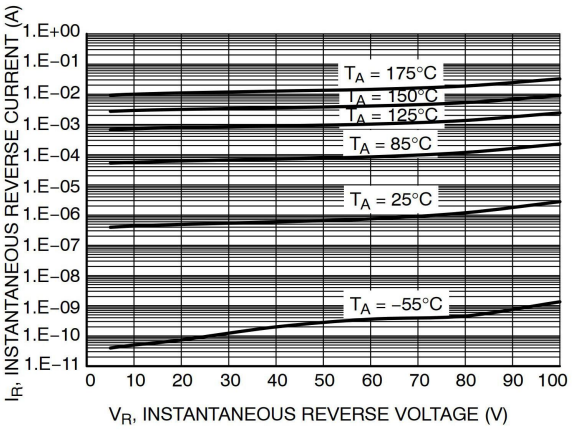


Figure 2. Typical Reverse Characteristics

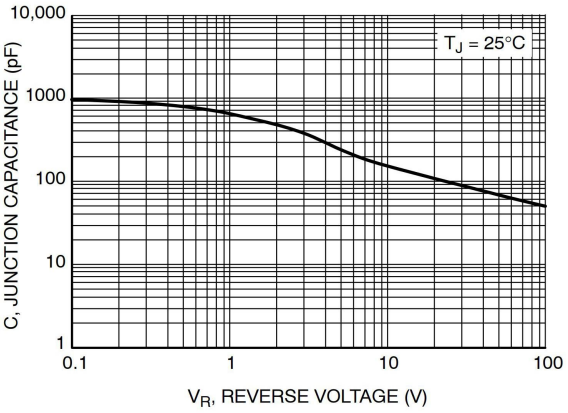


Figure 3. Typical Junction Capacitance

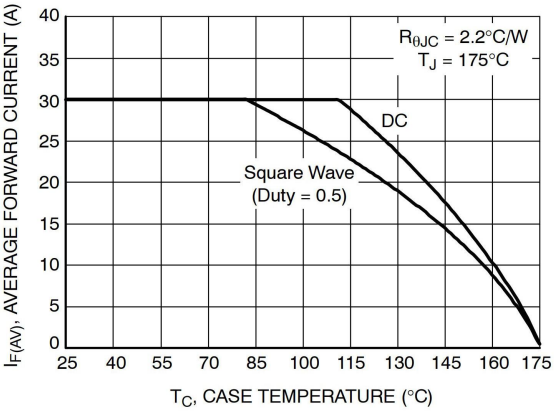


Figure 4. Current Derating

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TYPICAL CHARACTERISTICS

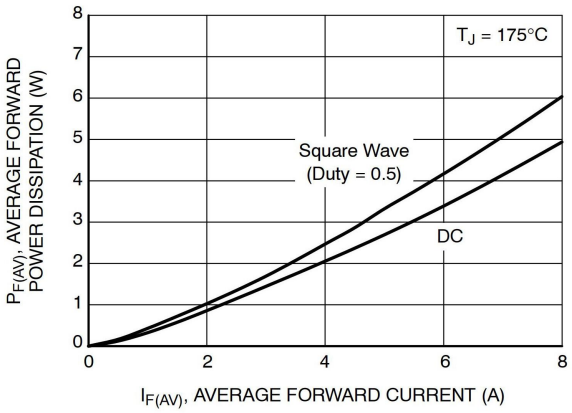


Figure 5. Forward Power Dissipation

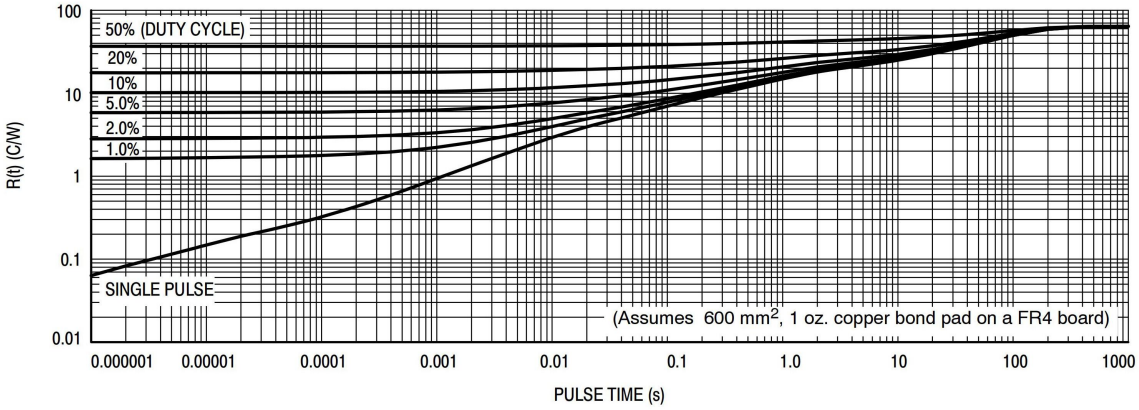


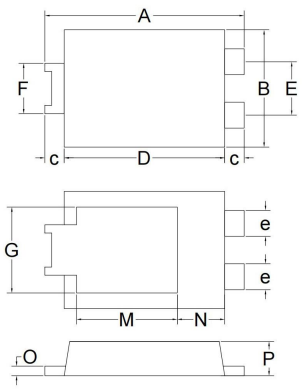
Figure 6. Typical Thermal Characteristics, Junction−to−Ambient

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Ordering Information

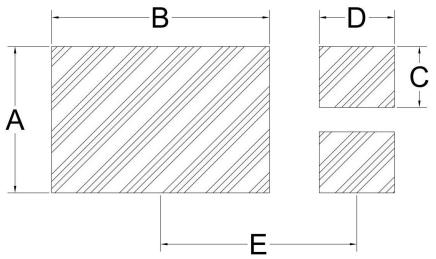
PACKAGE	PACKAGE CODE	UNIT WEIGHT(g)	REEL(pcs)	BOX(pcs)	CARTON(pcs)	DELIVERY MODE
TO-277	R3	0.090	5000	10000	100000	13''

Package Outline Dimensions (TO-277)



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	6.300	6.700	0.248	0.264
B	3.950	4.300	0.156	0.169
c	0.410	0.710	0.016	0.028
D	5.280	5.880	0.208	0.231
E	1.760	1.960	0.069	0.077
e	0.850	0.960	0.033	0.038
F	1.750	1.850	0.069	0.073
G	2.850	3.150	0.112	0.124
M	3.390	3.690	0.133	0.145
N	1.440	1.740	0.057	0.069
O	0.250	0.350	0.010	0.014
P	0.950	1.250	0.037	0.049

Suggested Pad Layout



Symbol	Dimensions			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	3.400	3.800	0.134	0.150
B	4.500	4.900	0.177	0.193
C	1.200	1.600	0.047	0.063
D	0.600	1.00	0.024	0.039
E	3.670	4.070	0.144	0.160